TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (U-MOSIII)

TPCS8208

Lithium Ion Battery Applications

Small footprint due to small and thin package

• Low drain-source ON resistance: $RDS(ON) = 13 \text{ m}\Omega \text{ (typ.)}$

• High forward transfer admittance: $|Y_{fs}| = 15 \text{ S (typ.)}$

• Low leakage current: $IDSS = 10 \mu A (max) (VDS = 20 V)$

• Enhancement mode: $V_{th} = 0.5 \sim 1.2 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 200 \text{ }\mu\text{A})$

• Common drain

Absolute Maximum Ratings (Ta = 25°C)

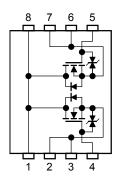
Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	20	V	
Drain-gate voltag	ge (R _{GS} = 20 kΩ)	V _{DGR}	20	V	
Gate-source volt	age	V _{GSS}	±12	V	
Drain current	DC (Note 1)	I _D	6	А	
Drain current	Pulse (Note 1)	I _{DP}	20 20 ±12	А	
Drain power	Single-device operation (Note 3a)	P _{D (1)}	1.1		
dissipation (t = 10 s) (Note 2a)	Single-device value at dual operation (Note 3b)	P _{D (2)}	0.75	W	
Drain power dissipation (t = 10 s) (Note 2b)	Single-device operation (Note 3a)	P _{D (1)}	0.6		
	Single-device value at dual operation (Note 3b)	P _{D (2)}	0.35	W	
Single pulse avalanche energy (Note 4)		E _{AS}	46.8	mJ	
Avalanche current		I _{AR}	6	Α	
Repetitive avalanche energy Single-device value at dual operation (Note 2a, 3b, 5)		E _{AR}	0.075	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	

Weight: 0.035 g (typ.)

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Circuit Configuration

2-3R1E



Note: (Note 1), (Note 2), (Note 3), (Note 4), (Note 5): See the next page.

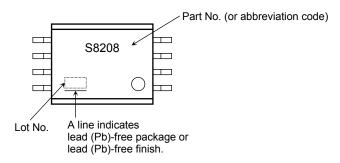
Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

This transistor is an electrostatic-sensitive device. Please handle with caution.

Thermal Characteristics

Characteristics	Symbol	Max	Unit		
	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	114	°C/W	
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	Single-device value at dual operation (Note 3b)	R _{th (ch-a) (2)}	167		
Thermal resistance, channel to ambient	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	(1) 208		
(t = 10 s) (Note 2b)	Single-device value at dual operation (Note 3b)	R _{th (ch-a) (2)}	357	°C/W	

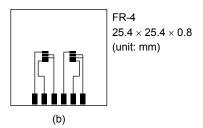
Marking (Note 6)



Note 1: Ensure that the channel temperature does not exceed 150°C.

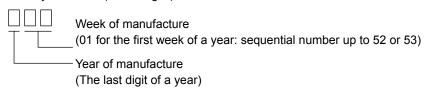
Note 2:

- a) Device mounted on a glass-epoxy board (a)
 - FR-4 25.4 × 25.4 × 0.8 (unit: mm)
- b) Device mounted on a glass-epoxy board (b)



Note 3:

- a) The power dissipation and thermal resistance values are shown for a single device (During single-device operation, power is only applied to one device.)
- b) The power dissipation and thermal resistance values are shown for a single device (During dual operation, power is evenly applied to both devices.)
- Note 4: $V_{DD}=16~V,~T_{ch}=25^{\circ}C$ (initial), $L=1.0~mH,~R_{G}=25~\Omega,~I_{AR}=6~A$
- Note 5: Repetitive rating: pulse width limited by maximum channel temperature
- Note 6: on lower right of the marking indicates Pin 1.
 - Weekly code: (Three digits)



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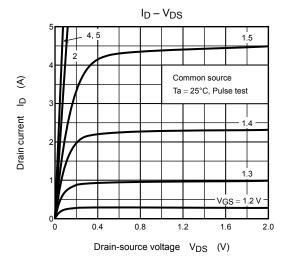
Electrical Characteristics (Ta = 25°C)

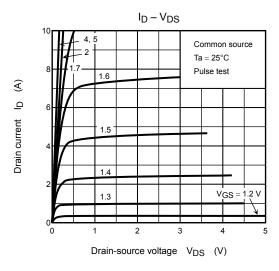
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cui	rrent	I _{GSS}	$V_{GS} = \pm 10 \text{ V}, V_{DS} = 0 \text{ V}$	±10		μА	
Drain cut-OFF cเ	ırrent	I _{DSS}	V _{DS} = 20 V, V _{GS} = 0 V	_			μА
Drain source bro	Cate leakage current Drain cut-OFF current Drain-source breakdown voltage Cate threshold voltage Drain-source ON resistance Corward transfer admittance Input capacitance Reverse transfer capacitance Dutput capacitance Rise time Turn-ON time	V _{(BR) DSS}	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	20	_	_	V
Diam-source bre	ardown voltage	V _{(BR) DSX}	$I_D = 10 \text{ mA}, V_{GS} = -12 \text{ V}$	8			V
Gate threshold ve	oltage	V _{th}			1.2	V	
			$V_{GS} = 2.0 \text{ V}, I_D = 4.2 \text{ A}$		24	35	
Drain-source ON resistance		R _{DS} (ON)	$V_{GS} = 2.5 \text{ V}, I_D = 4.2 \text{ A}$	_	18	22	mΩ
			V _{GS} = 4.0 V, I _D = 4.8 A	_	13	17	
Forward transfer	admittance	Y _{fs}	V _{DS} = 10 V, I _D = 3.0 A	7.5	15	_	S
Input capacitance		C _{iss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	2160	_	pF
Reverse transfer capacitance		C _{rss}		_	210	_	
Output capacitance		C _{oss}		_	230	_	
Drain cut-OFF current Drain-source breakdown voltage Gate threshold voltage Drain-source ON resistance Forward transfer admittance Input capacitance Reverse transfer capacitance Output capacitance Rise time Turn-ON time Fall time	Rise time	t _r	V _{GS} 5 V	_	5	_	- ns
	Turn-ON time	t _{on}		l	13	ı	
	Fall time	t _f			10		
	Turn-OFF time	t _{off}	V _{DD} ≃ 10 V Duty ≦ 1%, t _w = 10 μs	_	53	_	
		Qg		_	22	_	
Gate-source charge 1		Q _{gs1}	$V_{DD} \simeq 16 \text{ V}, V_{GS} = 5 \text{ V}, I_D = 6 \text{ A}$		4		nC
Gate-drain ("mille	er") charge	Q _{gd}		_	5		

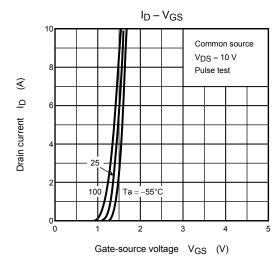
Source-Drain Ratings and Characteristics (Ta = 25°C)

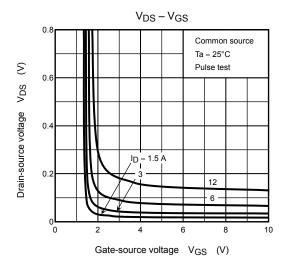
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I _{DRP}	_	_	_	24	Α
Forward voltage (diode)		V _{DSF}	I _{DR} = 6 A, V _{GS} = 0 V		_	-1.2	V

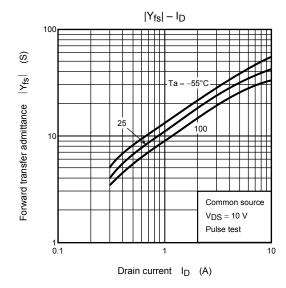
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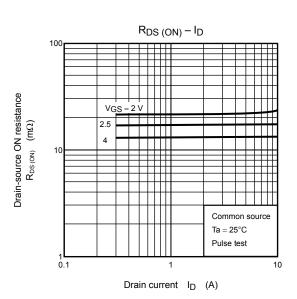


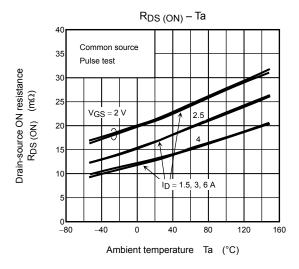


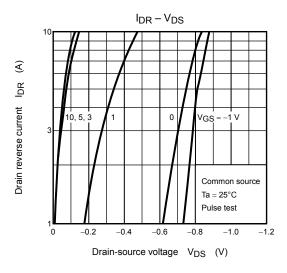


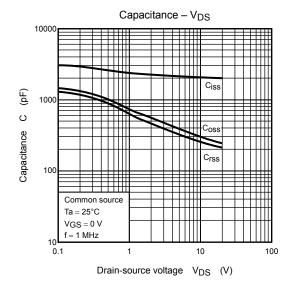


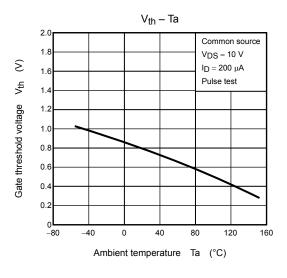


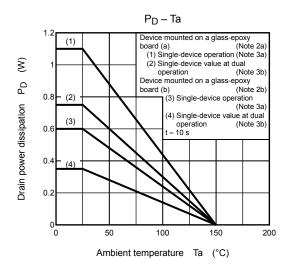


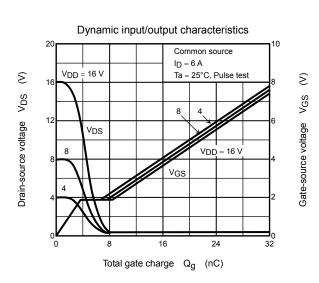


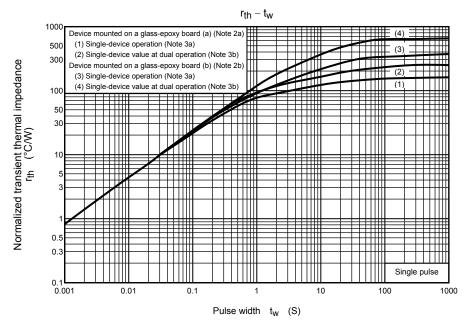




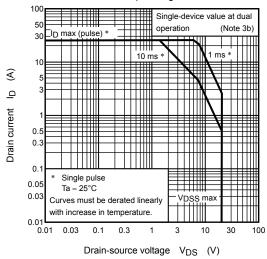












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